

Appl. No. 10/552,540
Amdt. Dated August 21, 2008
Reply to Office Action of May 21, 2008

Attorney Docket No. 81844.0044
Customer No. 26021

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of:

Shigeru TANAKA et al.

Serial No.: 10/552,540

Confirmation No.: 2300

Filed: October 11, 2005

For: THERMOSETTING RESIN
COMPOSITION, MULTILAYER BODY
USING SAME, AND CIRCUIT BOARD

Art Unit: 1796

Examiner: Patrick Dennis Niland

AMENDMENT

Mail Stop Amendment
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Dear Sir:

In response to the Final Office Action dated May 21, 2008, please amend the above-referenced application as follows:

Amendments to the Claims are reflected in the listing of claims which begins on page 2 of this paper.

Remarks/Arguments begin on page 19 of this paper.